

Application No.: 10/797890

Case No.: 59474US002

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**LISTING OF CLAIMS**

The following list of claims will replace all prior versions of claims in the application:

1. (original) A wafer planarization system comprising:  
an electrical source having a first electrode and a second electrode;  
a polishing pad carrier connected to said first electrode;  
a workpiece carrier connected to said second electrode;  
a conditioning tool comprising an abrasive surface adapted to condition said polishing pad; and  
an electrical insulator configured to isolate said abrasive surface from at least one of said first electrode and said second electrode.
2. (original) The system of claim 1 wherein said conditioning tool comprises said electrical insulator.
3. (original) The system of claim 2 wherein said wafer planarization system is an electro-chemical planarization system, said first electrode is a cathode, and said second electrode is an anode.
4. (original) The system of claim 2 wherein said conditioning tool further comprises an electrically insulated conditioning disk comprising said abrasive surface and a substrate proximate said abrasive surface.
5. (original) The system of claim 4 wherein said conditioning disk further comprises a carrier affixed to said substrate.
6. (original) The system of claim 5 wherein said carrier is an electrical insulator.

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7. (original) The system of claim 6 wherein said carrier is formed from polycarbonate.
8. (original) The system of claim 4 wherein said substrate is conductive.
9. (original) The system of claim 8 wherein said substrate comprises nickel.
10. (original) The system of claim 9 wherein said abrasive surface comprises a plurality of abrasive particles affixed to said substrate with a metal matrix.
11. (original) The system of claim 10 wherein said abrasive particles comprise diamonds.
12. (original) The system of claim 10 wherein said metal matrix comprises nickel.
13. (original) A method of conditioning an electrochemical-mechanical polishing pad comprising:  
electrically insulating an abrasive surface of a conditioning tool;  
contacting said abrasive surface with said polishing pad; and  
moving said abrasive surface relative to said polishing pad.
14. (original) The method of claim 13 wherein said conditioning tool further comprises an electrically insulated conditioning disk comprising a substrate proximate said abrasive surface and a carrier affixed to said substrate.
15. (original) The method of claim 14 wherein said carrier is an electrical insulator.

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16. (original) The method of claim 15 wherein said carrier is formed from polycarbonate.

17-20. (canceled).